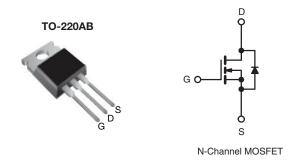
Vishay Siliconix

COMPLIANT HALOGEN

FREE

E Series Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	550				
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V 0.243				
Q _g max. (nC)	66				
Q _{gs} (nC)	8				
Q _{gd} (nC)	14				
Configuration	Single				



FEATURES

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

APPLICATIONS

- Computing
 - PC silver box / ATX power supplies
- Lighting
 - Two stage LED lighting
- Consumer electronics
- Applications using hard switched topologies
 - Power factor correction (PFC)
 - Two switch forward converter
 - Flyback converter
- Switch mode power supplies (SMPS)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and Halogen-free	SiHP15N50E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 ^{\circ}C$, un	less otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	500	V
Gate-Source Voltage	V_{GS}	± 30	v		
Continuous Drain Current (T _J = 150 °C)	V at 10 V	T _C = 25 °C T _C = 100 °C		14.5	
	V _{GS} at 10 V	T _C = 100 °C	I _D	9.2	А
Pulsed Drain Current ^a			I _{DM}	28	
Linear Derating Factor				1.25	W/°C
Single Pulse Avalanche Energy b			E _{AS}	136	mJ
Maximum Power Dissipation			P _D	156	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope V _{DS} = 0 V to 80 % V _{DS}		dV/dt	70	\//	
Reverse Diode dV/dt d			27	- V/ns	
Soldering Recommendations (Peak Temperature) c for 10 s			300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3.1 A.
- c. 1.6 mm from case.
- d. $I_{SD} \leq I_{D}, \; dI/dt = 100 \; A/\mu s, \; starting \; T_{J} = 25 \; ^{\circ}C.$

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W		
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.8			



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static						L	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	500	-	-	٧
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.62	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	٧
	I _{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-Source Leakage			$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zoro Coto Voltago Duoin Current		V _{DS} =	V _{DS} = 500 V, V _{GS} = 0 V		-	10	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 400 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	25	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 7.5 A	-	0.243	0.280	Ω
Forward Transconductance	9fs	V _{DS}	= 30 V, I _D = 7.5 A	-	3.9	-	S
Dynamic							
Input Capacitance	C _{iss}		$V_{GS} = 0 V$,	-	1162	-	
Output Capacitance	C _{oss}		$V_{DS} = 100 \text{ V},$	-	51	-	
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz	-	7	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	55	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	164	-	
Total Gate Charge	Qg			-	33	66	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 7.5 \text{ A}, V_{DS} = 400 \text{ V}$		8	-	nC
Gate-Drain Charge	Q_{gd}				14	-	
Turn-On Delay Time	t _{d(on)}	'		-	15	30	ns
Rise Time	t _r	V _{DD} -	$V_{DD} = 400 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V}, R_a = 9.1 \Omega$		24	48	
Turn-Off Delay Time	t _{d(off)}				34	68	
Fall Time	t _f		-	-	18	36	
Gate Input Resistance	R _g	f = 1 MHz, open drain		-	0.85	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	14.5	
Pulsed Diode Forward Current	I _{SM}			-	-	28	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 7.5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t _{rr}	$T_J = 25$ °C, $I_F = I_S = 7.5$ A, $I_F = 100$ A/ $I_F = $		-	265	-	ns
Reverse Recovery Charge	Q _{rr}			-	3.2	-	μC
Reverse Recovery Current	I _{RRM}			-	23	_	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

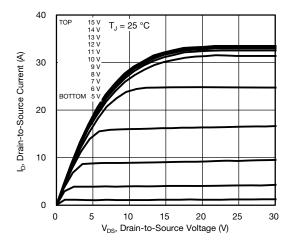


Fig. 1 - Typical Output Characteristics

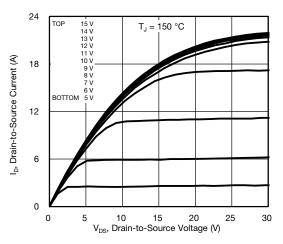


Fig. 2 - Typical Output Characteristics

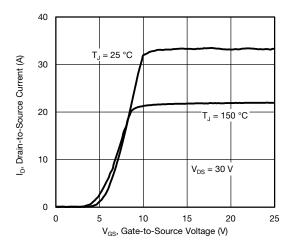


Fig. 3 - Typical Transfer Characteristics

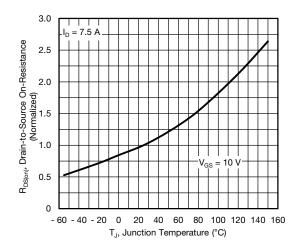


Fig. 4 - Normalized On-Resistance vs. Temperature

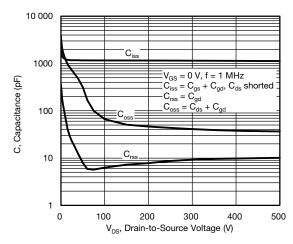


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

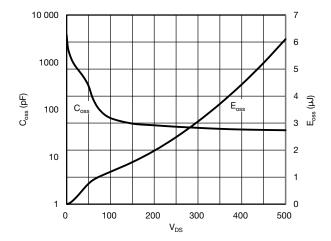


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



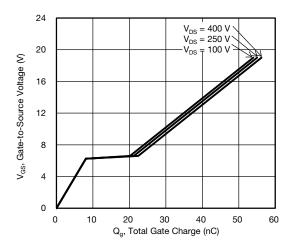


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

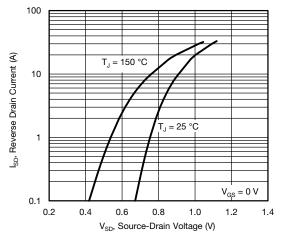


Fig. 8 - Typical Source-Drain Diode Forward Voltage

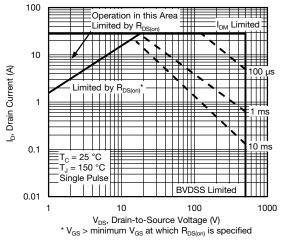


Fig. 9 - Maximum Safe Operating Area

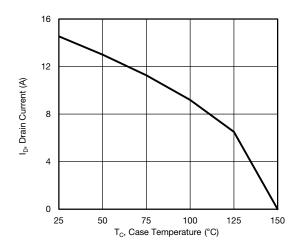


Fig. 10 - Maximum Drain Current vs. Case Temperature

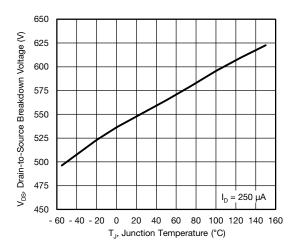


Fig. 11 - Temperature vs. Drain-to-Source Voltage



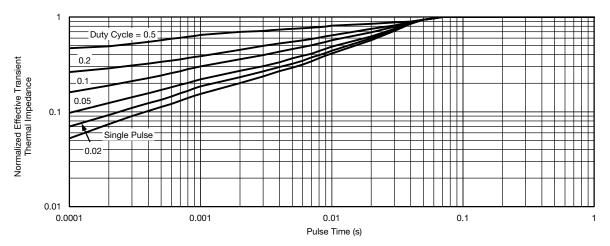


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

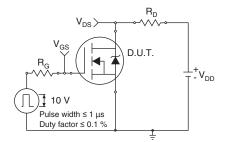


Fig. 13 - Switching Time Test Circuit

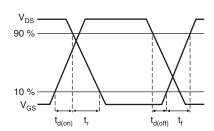


Fig. 14 - Switching Time Waveforms

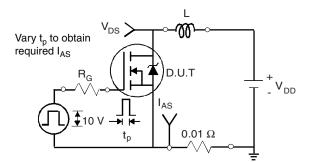


Fig. 15 - Unclamped Inductive Test Circuit

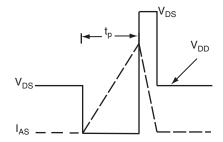


Fig. 16 - Unclamped Inductive Waveforms

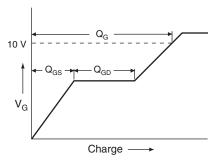


Fig. 17 - Basic Gate Charge Waveform

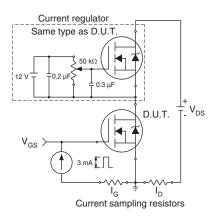
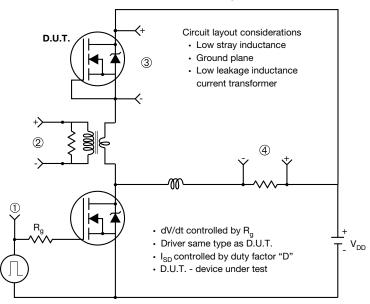


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



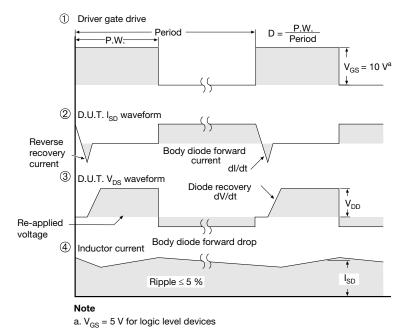


Fig. 19 - For N-Channel

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TO-220-1



DIM	MILLIN	IETERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.24	4.65	0.167	0.183		
b	0.69	1.02	0.027	0.040		
b(1)	1.14	1.78	0.045	0.070		
С	0.36	0.61	0.014	0.024		
D	14.33	15.85	0.564	0.624		
E	9.96	10.52	0.392	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.10	6.71	0.240	0.264		
J(1)	2.41	2.92	0.095	0.115		
L	13.36	14.40	0.526	0.567		
L(1)	3.33	4.04	0.131	0.159		
ØР	3.53	3.94	0.139	0.155		
Q	2.54	3.00	0.100	0.118		
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031						

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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